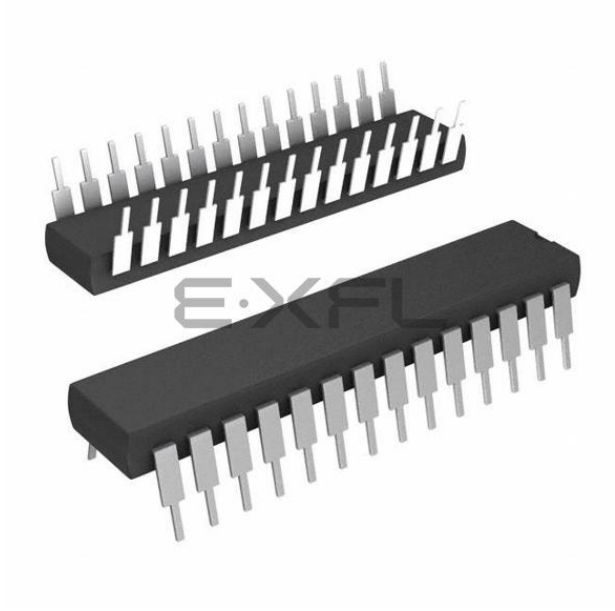

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	368 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f76-i-sp

2.2.2.1 STATUS Register

The STATUS register contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC, or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable, therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF, BSF, SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect the Z, C, or DC bits from the STATUS register. For other instructions not affecting any status bits, see the "Instruction Set Summary."

Note 1: The C and DC bits operate as a $\overline{borrow}$ and $\overline{digit\ borrow}$ bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 2-1: STATUS REGISTER (ADDRESS 03h, 83h, 103h, 183h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
`1` = Bank 2, 3 (100h - 1FFh)
`0` = Bank 0, 1 (00h - FFh)

bit 6-5 **RP1:RP0**: Register Bank Select bits (used for direct addressing)
`11` = Bank 3 (180h - 1FFh)
`10` = Bank 2 (100h - 17Fh)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes

bit 4 **$\overline{TO}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{borrow}$ bit (`ADDWF`, `ADDLW, SUBLW, SUBWF` instructions)
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

bit 0 **C:** Carry/$\overline{borrow}$ bit (`ADDWF, ADDLW, SUBLW, SUBWF` instructions)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{borrow}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF, RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.2.2.2 OPTION_REG Register

The OPTION_REG register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

Note:	To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

REGISTER 2-2: OPTION_REG REGISTER (ADDRESS 81h, 181h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7							bit 0

bit 7 **$\overline{\text{RBPU}}$**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6 **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5 **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4 **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3 **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
- n = Value at POR reset	’1’ = Bit is set	’0’ = Bit is cleared	x = Bit is unknown

2.2.2.8 PCON Register

The Power Control (PCON) register contains flag bits to allow differentiation between a Power-on Reset (POR), a Brown-out Reset (BOR), a Watchdog Reset (WDT) and an external MCLR Reset.

Note:	$\overline{BOR}$ is unknown on POR. It must be set by the user and checked on subsequent RESETS to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is not predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the configuration word).

REGISTER 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

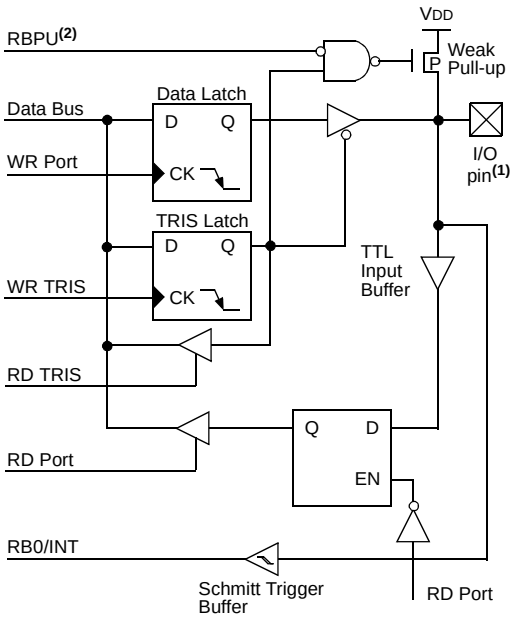
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.2 PORTB and the TRISB Register

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. Setting a TRISB bit (= '1') will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISB bit (= '0') will make the corresponding PORTB pin an output (i.e., put the contents of the output latch on the selected pin).

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBPU}}$ (OPTION_REG<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 4-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

Four of the PORTB pins (RB7:RB4) have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are ORed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

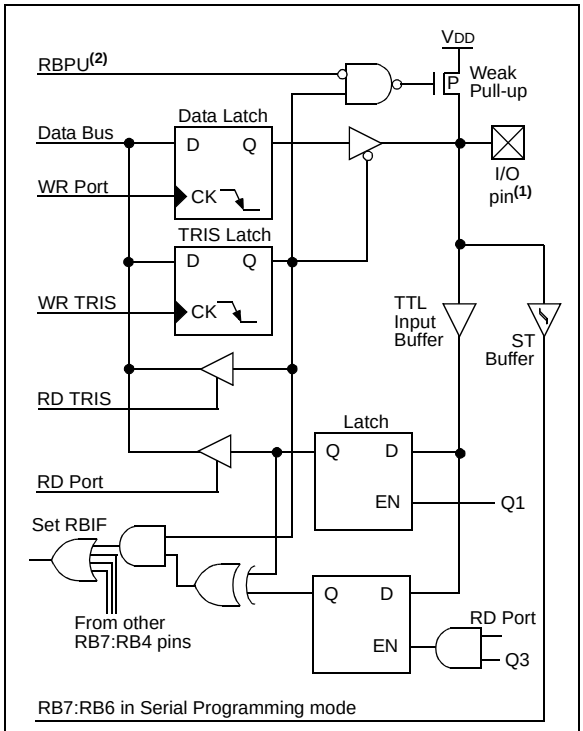
The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

This interrupt on mismatch feature, together with software configureable pull-ups on these four pins, allow easy interface to a keypad and make it possible for wake-up on key depression. Refer to the Embedded Control Handbook, "Implementing Wake-up on Key Stroke" (AN552).

RB0/INT is an external interrupt input pin and is configured using the INTEDG bit (OPTION_REG<6>).

RB0/INT is discussed in detail in Section 12.11.1.

FIGURE 4-4: BLOCK DIAGRAM OF RB7:RB4 PINS



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (OPTION_REG<7>).

4.6 Parallel Slave Port

The Parallel Slave Port (PSP) is not implemented on the PIC16F73 or PIC16F76.

PORTD operates as an 8-bit wide Parallel Slave Port, or Microprocessor Port, when control bit PSPMODE (TRISE<4>) is set. In Slave mode, it is asynchronously readable and writable by an external system using the read control input pin RE0/$\overline{RD}$, the write control input pin RE1/$\overline{WR}$, and the chip select control input pin RE2/$\overline{CS}$.

The PSP can directly interface to an 8-bit microprocessor data bus. The external microprocessor can read or write the PORTD latch as an 8-bit latch. Setting bit PSPMODE enables port pin RE0/$\overline{RD}$ to be the $\overline{RD}$ input, RE1/$\overline{WR}$ to be the $\overline{WR}$ input and RE2/$\overline{CS}$ to be the $\overline{CS}$ (chip select) input. For this functionality, the corresponding data direction bits of the TRISE register (TRISE<2:0>) must be configured as inputs (i.e., set). The A/D port configuration bits PCFG3:PCFG0 (ADCON1<3:0>) must be set to configure pins RE2:RE0 as digital I/O.

There are actually two 8-bit latches, one for data output (external reads) and one for data input (external writes). The firmware writes 8-bit data to the PORTD output data latch and reads data from the PORTD input data latch (note that they have the same address). In this mode, the TRISD register is ignored, since the external device is controlling the direction of data flow.

An external write to the PSP occurs when the $\overline{CS}$ and $\overline{WR}$ lines are both detected low. Firmware can read the actual data on the PORTD pins during this time. When either the CS or WR lines become high (level triggered), the data on the PORTD pins is latched, and the Input Buffer Full (IBF) status flag bit (TRISE<7>) and interrupt flag bit PSPIF (PIR1<7>) are set on the Q4 clock cycle, following the next Q2 cycle to signal the write is complete (Figure 4-9). Firmware clears the IBF flag by reading the latched PORTD data, and clears the PSPIF bit.

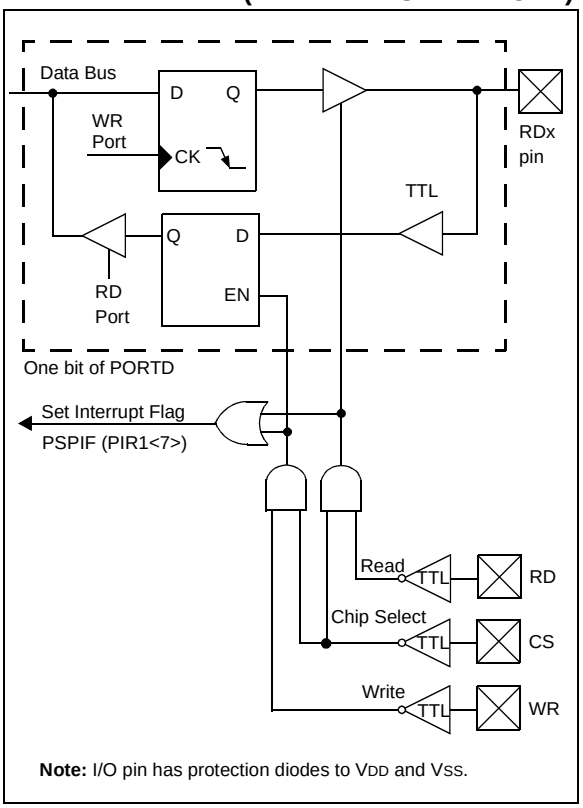
The Input Buffer Overflow (IBOV) status flag bit (TRISE<5>) is set if an external write to the PSP occurs while the IBF flag is set from a previous external write. The previous PORTD data is overwritten with the new data. IBOV is cleared by reading PORTD and clearing IBOV.

A read from the PSP occurs when both the $\overline{CS}$ and $\overline{RD}$ lines are detected low. The data in the PORTD output latch is output to the PORTD pins. The Output Buffer Full (OBF) status flag bit (TRISE<6>) is cleared immediately (Figure 4-10), indicating that the PORTD latch is being read, or has been read by the external bus. If firmware writes new data to the output latch during this time, it is immediately output to the PORTD pins, but OBF will remain cleared.

When either the $\overline{CS}$ or $\overline{RD}$ pins are detected high, the PORTD outputs are disabled, and the interrupt flag bit PSPIF is set on the Q4 clock cycle following the next Q2 cycle, indicating that the read is complete. OBF remains low until firmware writes new data to PORTD.

When not in PSP mode, the IBF and OBF bits are held clear. Flag bit IBOV remains unchanged. The PSPIF bit must be cleared by the user in firmware; the interrupt can be disabled by clearing the interrupt enable bit PSPIE (PIE1<7>).

FIGURE 4-8: PORTD AND PORTE BLOCK DIAGRAM (PARALLEL SLAVE PORT)



Note: I/O pin has protection diodes to V_{DD} and V_{SS}.

6.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during SLEEP and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (Section 6.4.1).

In Asynchronous Counter mode, Timer1 cannot be used as a time-base for capture or compare operations.

6.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. The example code provided in Example 6-1 and Example 6-2 demonstrates how to write to and read Timer1 while it is running in Asynchronous mode.

EXAMPLE 6-1: WRITING A 16-BIT FREE-RUNNING TIMER

```
; All interrupts are disabled
CLRF    TMR1L       ; Clear Low byte, Ensures no rollover into TMR1H
MOVLW   HI_BYTE     ; Value to load into TMR1H
MOVWF   TMR1H, F    ; Write High byte
MOVLW   LO_BYTE     ; Value to load into TMR1L
MOVWF   TMR1H, F    ; Write Low byte
; Re-enable the Interrupt (if required)
CONTINUE            ; Continue with your code
```

EXAMPLE 6-2: READING A 16-BIT FREE-RUNNING TIMER

```
; All interrupts are disabled
MOVF    TMR1H, W    ; Read high byte
MOVWF   TMPH
MOVF    TMR1L, W    ; Read low byte
MOVWF   TMPL
MOVF    TMR1H, W    ; Read high byte
SUBWF   TMPH,  W    ; Sub 1st read with 2nd read
BTFSC   STATUS,Z    ; Is result = 0
GOTO    CONTINUE    ; Good 16-bit read
; TMR1L may have rolled over between the read of the high and low bytes.
; Reading the high and low bytes now will read a good value.
MOVF    TMR1H, W    ; Read high byte
MOVWF   TMPH
MOVF    TMR1L, W    ; Read low byte
MOVWF   TMPL        ; Re-enable the Interrupt (if required)
CONTINUE            ; Continue with your code
```

REGISTER 8-1: CCP1CON REGISTER/CCP2CON REGISTER (ADDRESS: 17h/1Dh)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CCPxX	CCPxY	CCPxM3	CCPxM2	CCPxM1	CCPxM0
bit 7							bit 0

bit 7-6 **Unimplemented:** Read as '0'

bit 5-4 **CCPxX:CCPxY**: PWM Least Significant bits

Capture mode:
Unused

Compare mode:
Unused

PWM mode:
These bits are the two LSbs of the PWM duty cycle. The eight MSbs are found in CCPRxL.

bit 3-0 **CCPxM3:CCPxM0**: CCPx Mode Select bits

0000 = Capture/Compare/PWM disabled (resets CCPx module)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCPxIF bit is set)
1001 = Compare mode, clear output on match (CCPxIF bit is set)
1010 = Compare mode, generate software interrupt on match (CCPxIF bit is set, CCPx pin is unaffected)
1011 = Compare mode, trigger special event (CCPxIF bit is set, CCPx pin is unaffected); CCP1 clears Timer1; CCP2 clears Timer1 and starts an A/D conversion (if A/D module is enabled)
11xx = PWM mode

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

12.0 SPECIAL FEATURES OF THE CPU

These devices have a host of features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator Selection
- RESET
  - Power-on Reset (POR)
  - Power-up Timer (PWRT)
  - Oscillator Start-up Timer (OST)
  - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP
- Code Protection
- ID Locations
- In-Circuit Serial Programming

These devices have a Watchdog Timer, which can be enabled or disabled, using a configuration bit. It runs off its own RC oscillator for added reliability.

There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only. It is designed to keep the part in RESET while the power supply stabilizes, and is enabled or disabled, using a configuration bit. With these two timers on-chip, most applications need no external RESET circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through external RESET, Watchdog Timer Wake-up, or through an interrupt.

Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. Configuration bits are used to select the desired oscillator mode.

Additional information on special features is available in the PICmicro™ Mid-Range Reference Manual (DS33023).

12.1 Configuration Bits

The configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space, which can be accessed only during programming.

12.11 Interrupts

The PIC16F7X family has up to 12 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all unmasked interrupts, or disables (if cleared) all interrupts. When bit GIE is enabled and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set, regardless of the status of the GIE bit. The GIE bit is cleared on RESET.

The "return from interrupt" instruction, `RETFIE`, exits the interrupt routine, as well as sets the GIE bit, which re-enables interrupts.

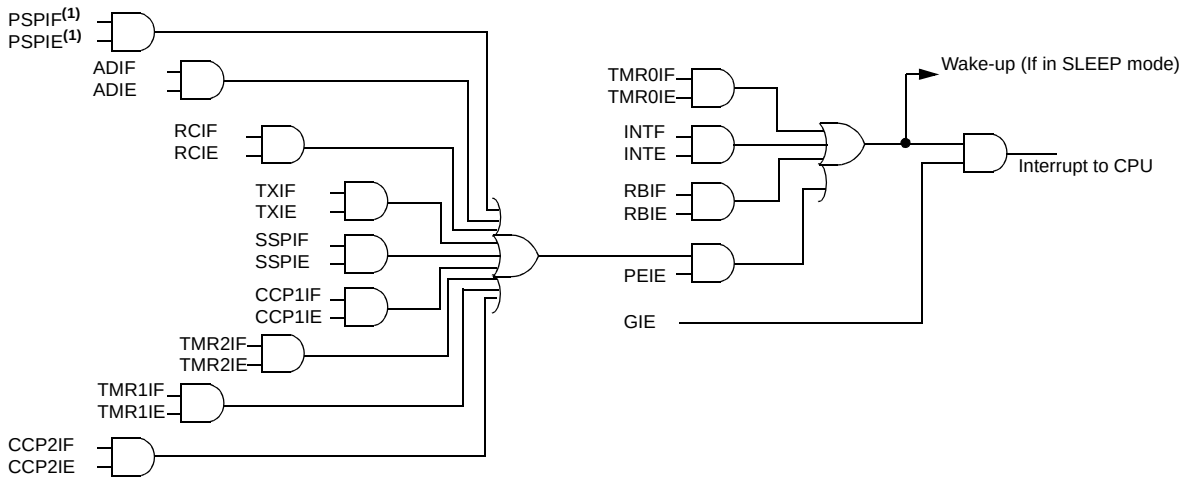
The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the Special Function Registers, PIR1 and PIR2. The corresponding interrupt enable bits are contained in Special Function Registers, PIE1 and PIE2, and the peripheral interrupt enable bit is contained in Special Function Register, INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs, relative to the current Q cycle. The latency is the same for one or two-cycle instructions. Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit, PEIE bit, or the GIE bit.

FIGURE 12-10: INTERRUPT LOGIC



Note 1: PSP interrupt is implemented only on PIC16F74/77 devices.

12.11.1 INT INTERRUPT

External interrupt on the RB0/INT pin is edge triggered, either rising, if bit INTEDG (OPTION_REG<6>) is set, or falling, if the INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, flag bit INTF (INTCON<1>) is set. This interrupt can be disabled by clearing enable bit INTE (INTCON<4>). Flag bit INTF must be cleared in software in the Interrupt Service Routine before re-enabling this interrupt. The INT interrupt can wake-up the processor from SLEEP, if bit INTE was set prior to going into SLEEP. The status of global interrupt enable bit GIE decides whether or not the processor branches to the interrupt vector following wake-up. See Section 12.14 for details on SLEEP mode.

12.11.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set flag bit TMR0IF (INTCON<2>). The interrupt can be enabled/disabled by setting/clearing enable bit TMR0IE (INTCON<5>). (Section 5.0)

12.11.3 PORTB INTCON CHANGE

An input change on PORTB<7:4> sets flag bit RBIF (INTCON<0>). The interrupt can be enabled/disabled by setting/clearing enable bit RBIE (INTCON<4>), see Section 4.2.

12.12 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (i.e., W, PCLATH and STATUS registers). This will have to be implemented in software, as shown in Example 12-1.

For the PIC16F73/74 devices, the register W_TEMP must be defined in both banks 0 and 1 and must be defined at the same offset from the bank base address (i.e., If W_TEMP is defined at 20h in bank 0, it must also be defined at A0h in bank 1.). The registers, PCLATH_TEMP and STATUS_TEMP, are only defined in bank 0.

Since the upper 16 bytes of each bank are common in the PIC16F76/77 devices, temporary holding registers W_TEMP, STATUS_TEMP and PCLATH_TEMP should be placed in here. These 16 locations don't require banking and, therefore, make it easier for context save and restore. The same code shown in Example 12-1 can be used.

EXAMPLE 12-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
    MOVWF   W_TEMP              ;Copy W to TEMP register
    SWAPF   STATUS,W            ;Swap status to be saved into W
    CLRF    STATUS              ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
    MOVWF   STATUS_TEMP         ;Save status to bank zero STATUS_TEMP register
    MOVF    PCLATH, W           ;Only required if using pages 1, 2 and/or 3
    MOVWF   PCLATH_TEMP         ;Save PCLATH into W
    CLRF    PCLATH              ;Page zero, regardless of current page
    :
    :(ISR)                      ;Insert user code here
    :
    MOVF    PCLATH_TEMP, W      ;Restore PCLATH
    MOVWF   PCLATH              ;Move W into PCLATH
    SWAPF   STATUS_TEMP,W       ;Swap STATUS_TEMP register into W
                                ;(sets bank to original state)
    MOVWF   STATUS              ;Move W into STATUS register
    SWAPF   W_TEMP,F            ;Swap W_TEMP
    SWAPF   W_TEMP,W            ;Swap W_TEMP into W
```

NOTES:

15.1 DC Characteristics: PIC16F73/74/76/77 (Industrial, Extended) PIC16LF73/74/76/77 (Industrial) (Continued)

PIC16LF73/74/76/77 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC16F73/74/76/77 (Industrial, Extended)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	IDD	**Supply Current (Notes 2, 5)**					
D010		PIC16LF7X	—	0.4	2.0	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V **(Note 4)**
D010A			—	20	48	µA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D010		PIC16F7X	-	0.9	4	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 5.5V **(Note 4)**
D013			—	5.2	15	mA	HS osc configuration FOSC = 20 MHz, VDD = 5.5V
D015*	ΔIBOR	**Brown-out Reset Current (Note 6)**	—	25	200	µA	BOR enabled, VDD = 5.0V
D020	IPD	**Power-down Current (Notes 3, 5)**					
		PIC16LF7X	—	2.0	30	µA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			—	0.1	5	µA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D020		PIC16F7X	—	5.0	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			—	0.1	19	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021A			—	10.5	57	µA	VDD = 4.0V, WDT enabled, -40°C to +125°C
			—	1.5	42	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023*	ΔIBOR	**Brown-out Reset Current (Note 6)**	—	25	200	µA	BOR enabled, VDD = 5.0V

Legend: Shading of rows is to assist in readability of of the table.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from-rail to-rail; all I/O pins tri-stated, pulled to VDD
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: When BOR is enabled, the device will operate correctly until the VBOR voltage trip point is reached.

TABLE 15-9: I^2C BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100*	THIGH	Clock high time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
90*	TSU:STA	START condition setup time	100 kHz mode	4.7	—	µs	Only relevant for Repeated START condition
			400 kHz mode	0.6	—	µs	
91*	THD:STA	START condition hold time	100 kHz mode	4.0	—	µs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	CB	Bus capacitive loading		—	400	pF	

* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A Fast mode (400 kHz) I^2C bus device can be used in a Standard mode (100 kHz) I^2C bus system, but the requirement $T_{SU:DAT} \geq 250$ ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line T_R max. + $T_{SU:DAT}$ = 1000 + 250 = 1250 ns (according to the Standard mode I^2C bus specification), before the SCL line is released.

NOTES:

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 16-1: TYPICAL IDD vs. FOSC OVER VDD (HS MODE)

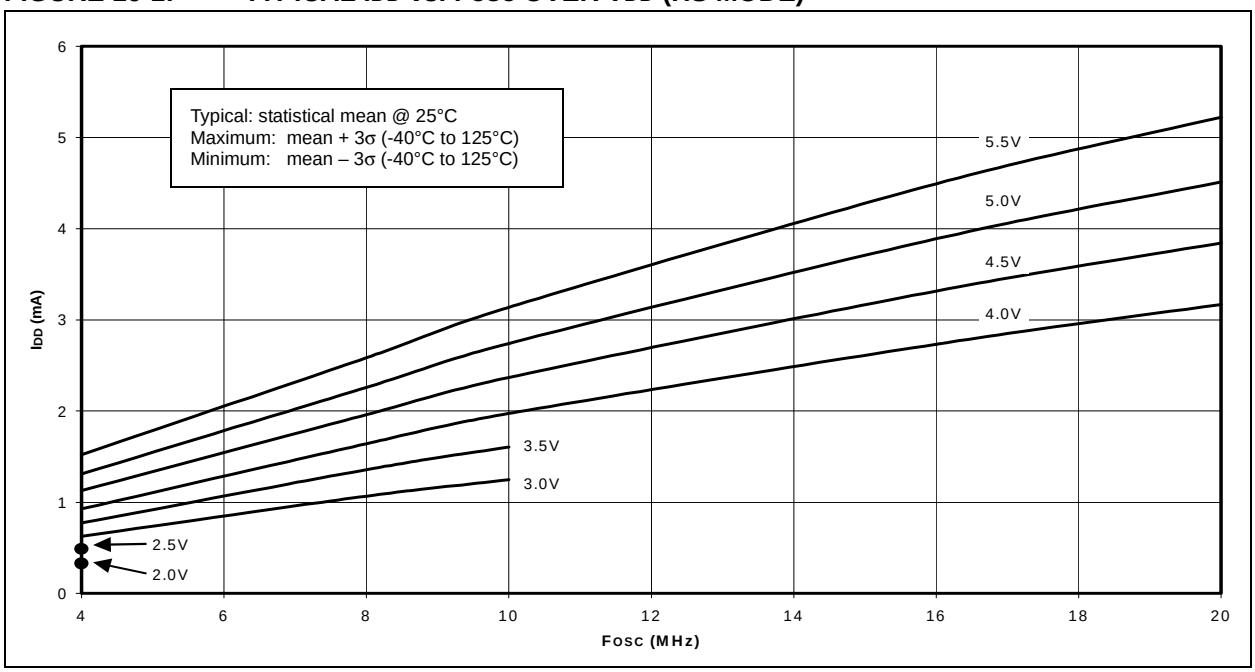


FIGURE 16-2: MAXIMUM IDD vs. FOSC OVER VDD (HS MODE)

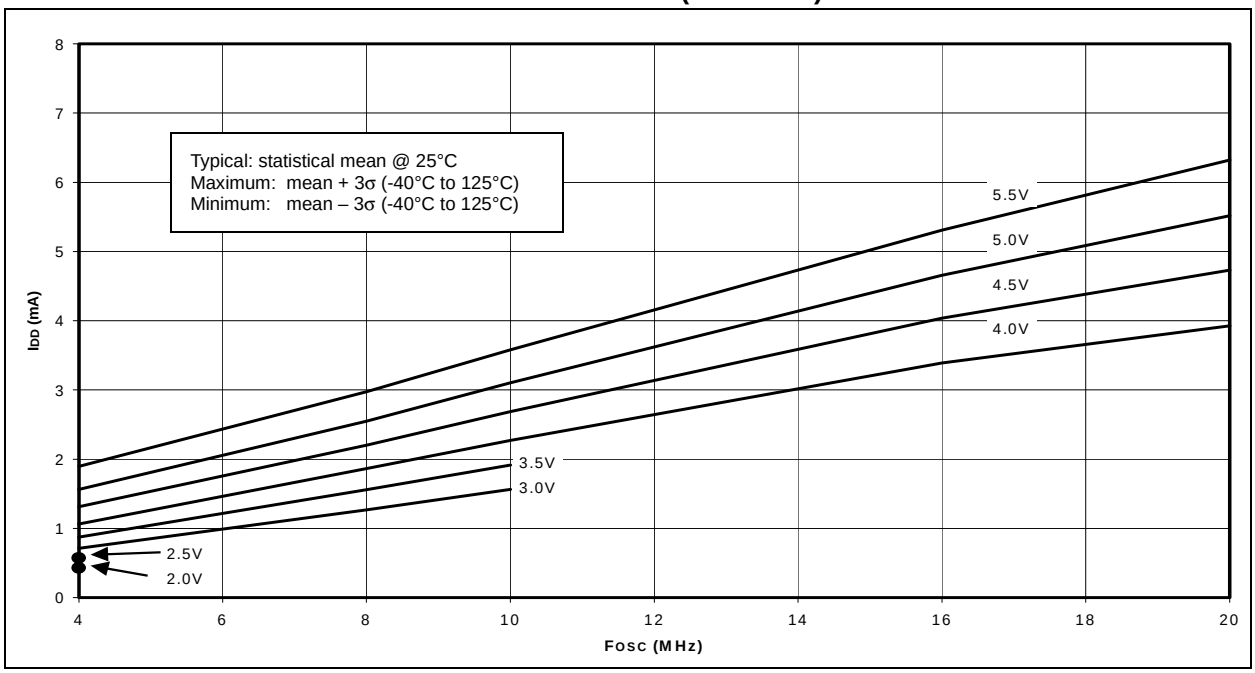


FIGURE 16-3: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

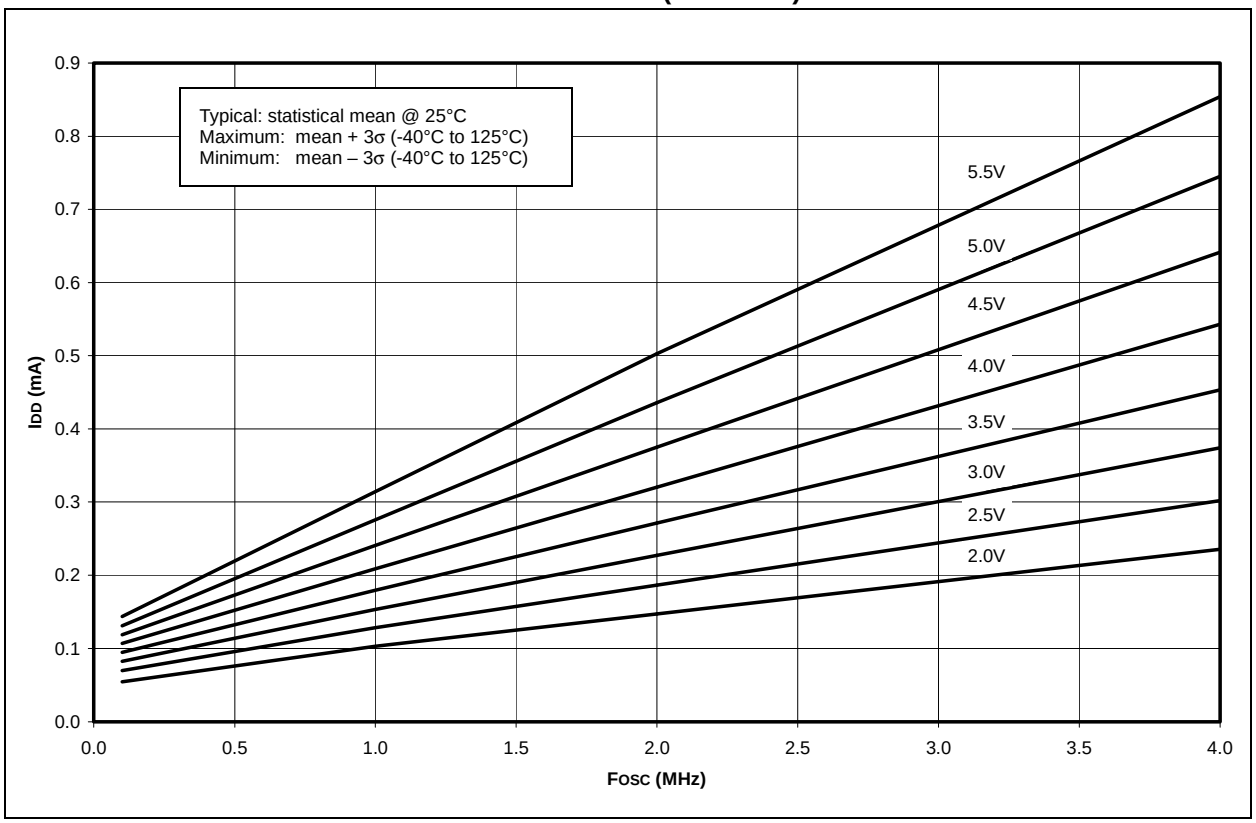
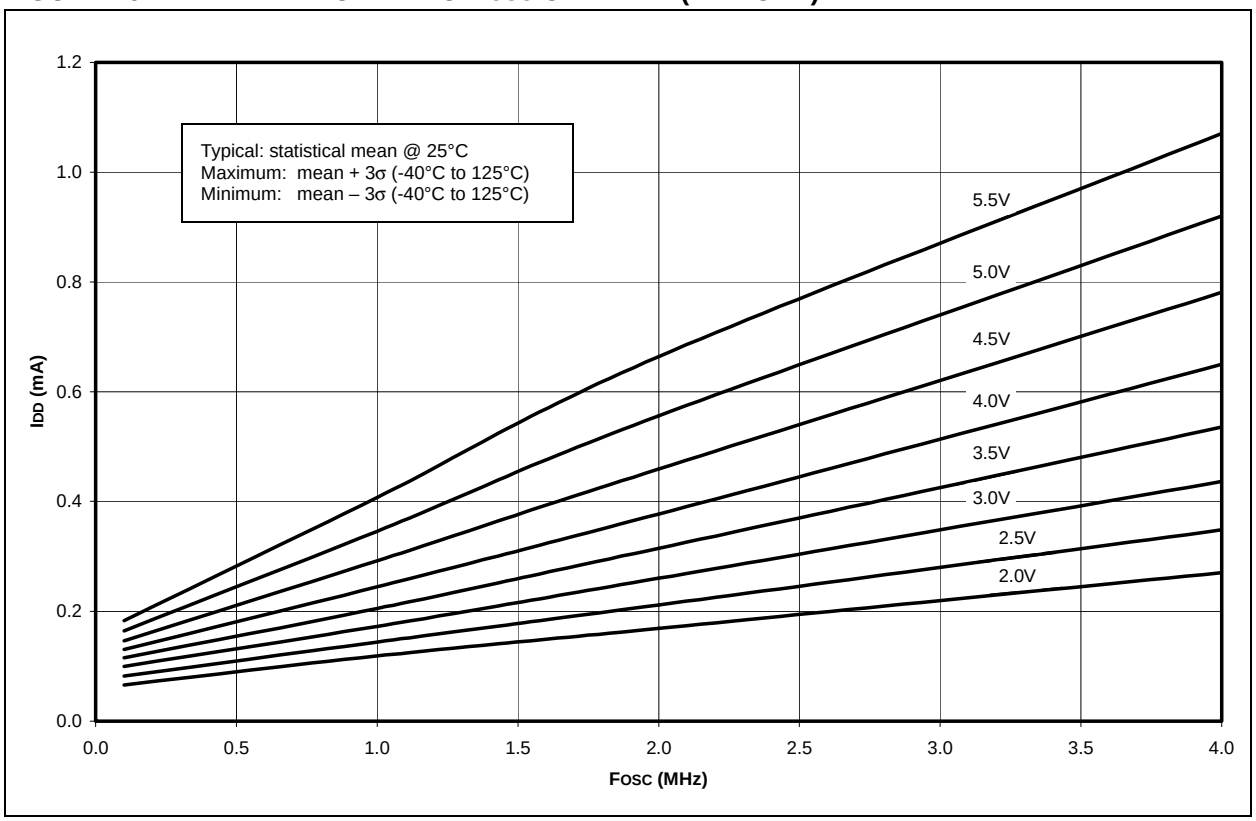
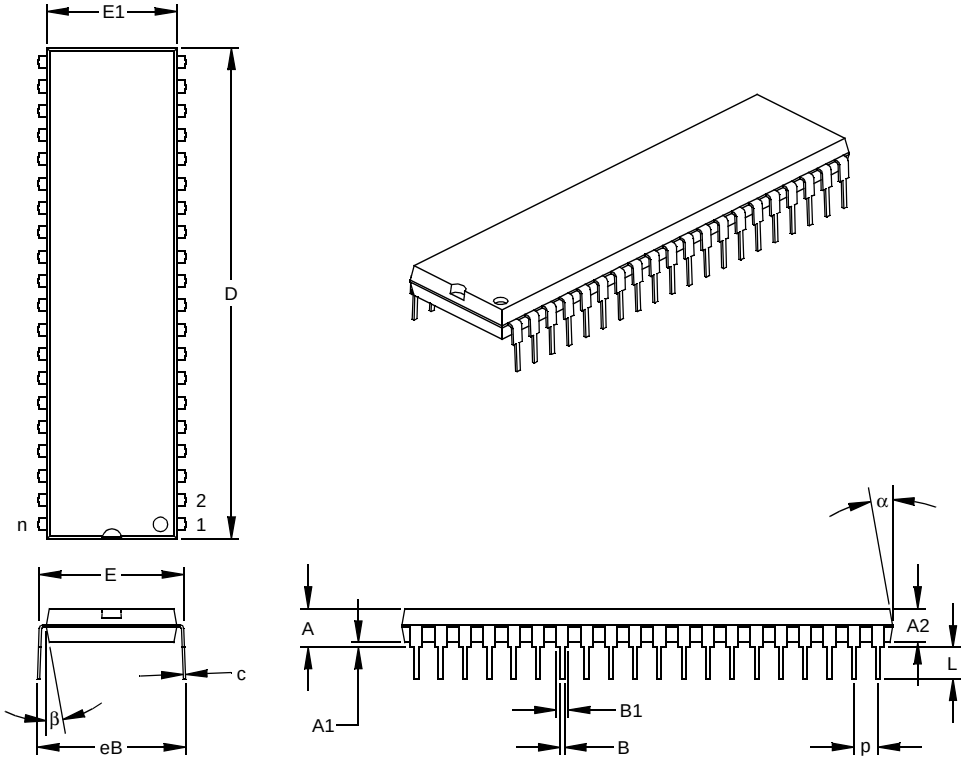


FIGURE 16-4: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)



40-Lead Plastic Dual In-line (P) – 600 mil (PDIP)

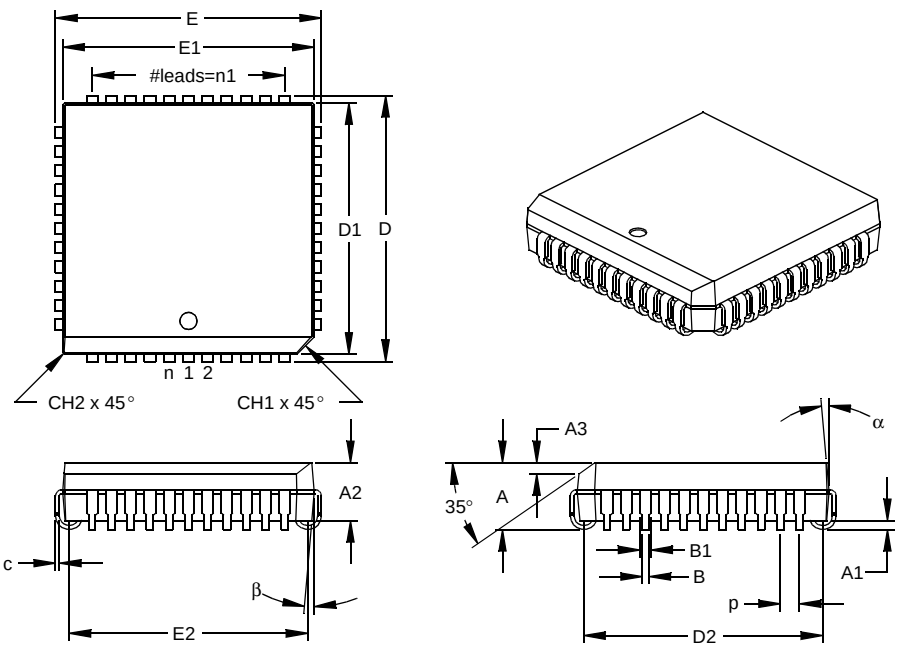


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		40			40	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.530	.545	.560	13.46	13.84	14.22
Overall Length	D	2.045	2.058	2.065	51.94	52.26	52.45
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-011
Drawing No. C04-016

44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-048

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2000	This is a new data sheet. However, these devices are similar to the PIC16C7X devices found in the PIC16C7X Data Sheet (DS30390) or the PIC16F87X devices (DS30292).
B	2001	Final data sheet. Includes device characterization data. Addition of extended temperature devices. Addition of 28-pin MLF package. Minor typographic revisions throughout.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices in this data sheet are listed in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Difference	PIC16F73	PIC16F74	PIC16F76	PIC16F77
FLASH Program Memory (14-bit words)	4K	4K	8K	8K
Data Memory (bytes)	192	192	368	368
I/O Ports	3	5	3	5
A/D	5 channels, 8 bits	8 channels, 8 bits	5 channels, 8 bits	8 channels, 8 bits
Parallel Slave Port	no	yes	no	yes
Interrupt Sources	11	12	11	12
Packages	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC

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